

# BFG505; BFG505/X

## **NPN 9 GHz wideband transistors**

Rev. 04 — 22 November 2007

**Product data sheet** 

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BFG505; BFG505/X

#### **FEATURES**

- High power gain
- Low noise figure
- · High transition frequency
- Gold metallization ensures excellent reliability.

### **APPLICATIONS**

RF front end applications in the GHz range, such as analog and digital cellular telephones, cordless telephones (CT1, CT2, DECT, etc.), radar detectors, pagers and satellite TV tuners (SATV).

#### **DESCRIPTION**

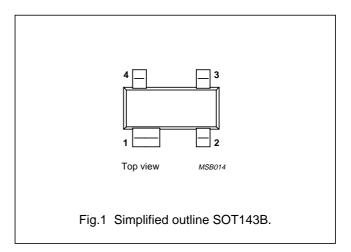
NPN silicon planar epitaxial transistor in a 4-pin dual-emitter SOT143B plastic package.

### **MARKING**

TYPE NUMBER	CODE
BFG505	%ME
BFG505/X	%MK

#### **PINNING**

PIN	DESCRIPTION				
PIN	BFG505	BFG505/X			
1	collector	collector			
2	base	emitter			
3	emitter	base			
4	emitter	emitter			



#### **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	_	20	V
V <sub>CES</sub>	collector-emitter voltage	$R_{BE} = 0$	_	_	15	V
I <sub>C</sub>	collector current (DC)		_	_	18	mA
P <sub>tot</sub>	total power dissipation	T <sub>s</sub> ≤ 130 °C	_	_	150	mW
h <sub>FE</sub>	DC current gain	$V_{CE} = 6 \text{ V}; I_{C} = 5 \text{ mA}$	60	120	250	
C <sub>re</sub>	feedback capacitance	$V_{CB} = 6 \text{ V}; I_C = i_c = 0; f = 1 \text{ MHz}$	_	0.2	_	pF
f <sub>T</sub>	transition frequency	$V_{CE} = 6 \text{ V}; I_{C} = 5 \text{ mA}; f = 1 \text{ GHz}$	_	9	_	GHz
G <sub>UM</sub>	maximum unilateral power gain	$V_{CE} = 6 \text{ V}; I_{C} = 5 \text{ mA};$ $T_{amb} = 25 \text{ °C}; f = 900 \text{ MHz}$	_	20	_	dB
		$V_{CE} = 6 \text{ V; } I_{C} = 5 \text{ mA;}$ $T_{amb} = 25 \text{ °C; } f = 2 \text{ GHz}$	_	13	_	dB
S <sub>21</sub>   <sup>2</sup>	insertion power gain	$V_{CE} = 6 \text{ V; } I_{c} = 5 \text{ mA;}$ $T_{amb} = 25 \text{ °C; } f = 900 \text{ MHz}$	16	17	_	dB
F	noise figure	$\Gamma_{\rm S} = \Gamma_{\rm opt}$ ; $V_{\rm CE} = 6$ V; $I_{\rm c} = 1.25$ mA; $T_{\rm amb} = 25$ °C; $f = 900$ MHz	_	1.2	1.7	dB
		$\Gamma_{\rm S} = \Gamma_{\rm opt}$ ; $V_{\rm CE} = 6$ V; $I_{\rm c} = 5$ mA; $T_{\rm amb} = 25$ °C; $f = 900$ MHz	_	1.6	2.1	dB
		$\Gamma_{\text{S}} = \Gamma_{\text{opt}}; \ V_{\text{CE}} = 6 \ \text{V}; \ I_{\text{c}} = 1.25 \ \text{mA}; \ T_{\text{amb}} = 25 \ ^{\circ}\text{C}; \ f = 2 \ \text{GHz}$	_	1.9	_	dB

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### **LIMITING VALUES**

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	20	V
V <sub>CES</sub>	collector-emitter voltage	R <sub>BE</sub> = 0	_	15	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	2.5	V
I <sub>C</sub>	collector current (DC)		_	18	mA
P <sub>tot</sub>	total power dissipation	T <sub>s</sub> ≤ 130 °C; see Fig.2; note 1	_	150	mW
T <sub>stg</sub>	storage temperature range		-65	150	°C
Tj	junction temperature		_	175	°C

#### Note

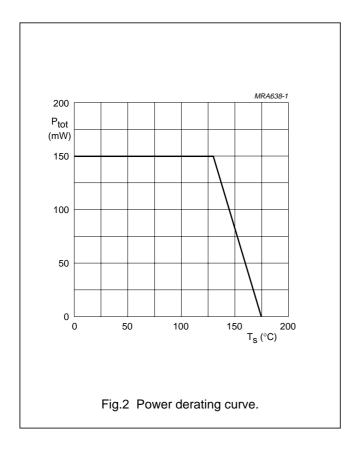
1.  $T_s$  is the temperature at the soldering point of the collector pin.

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-s</sub>	thermal resistance from junction to soldering point	note 1	290	K/W

#### Note

1.  $T_{\text{S}}$  is the temperature at the soldering point of the collector pin.



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#### **CHARACTERISTICS**

 $T_j = 25$  °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector cut-off current	V <sub>CB</sub> = 6 V; I <sub>E</sub> = 0	_	_	50	nA
h <sub>FE</sub>	DC current gain	$I_C = 5 \text{ mA}$ ; $V_{CE} = 6 \text{ V}$ ; see Fig.3	60	120	250	
C <sub>e</sub>	emitter capacitance	$I_C = I_c = 0 V_{EB} = 0.5 V; f = 1 MHz$	_	0.4	_	pF
C <sub>c</sub>	collector capacitance	$V_{CB} = 6 \text{ V}; I_E = i_e = 0; f = 1 \text{ MHz}$	_	0.3	_	pF
C <sub>re</sub>	feedback capacitance	I <sub>C</sub> = 0; V <sub>CB</sub> = 6 V; f = 1 MHz; see Fig.4	_	0.2	_	pF
f <sub>T</sub>	transition frequency	I <sub>C</sub> = 5 mA; V <sub>CE</sub> = 6 V; f = 1 GHz; see Fig.5	_	9	_	GHz
G <sub>UM</sub>	maximum unilateral power gain; note 1	I <sub>C</sub> = 5 mA; V <sub>CE</sub> = 6 V; T <sub>amb</sub> = 25 °C; f = 900 MHz	_	20	_	dB
		$I_c = 5 \text{ mA}; V_{CE} = 6 \text{ V};$ $T_{amb} = 25 \text{ °C}; f = 2 \text{ GHz}$	_	13	_	dB
S <sub>21</sub>   <sup>2</sup>	insertion power gain	$I_c = 5 \text{ mA}; V_{CE} = 6 \text{ V};$ $T_{amb} = 25 \text{ °C}; f = 900 \text{ MHz}$	16	17	_	dB
F	noise figure	$\Gamma_{\text{s}} = \Gamma_{\text{opt}}$ ; $I_{\text{C}} = 1.25$ mA; $V_{\text{CE}} = 6$ V; $T_{\text{amb}} = 25$ °C; $f = 900$ MHz	_	1.2	1.7	dB
		$\Gamma_{\text{s}} = \Gamma_{\text{opt}}$ ; $I_{\text{C}} = 5$ mA; $V_{\text{CE}} = 6$ V; $T_{\text{amb}} = 25$ °C; $f = 900$ MHz	_	1.6	2.1	dB
		$\Gamma_{\text{s}} = \Gamma_{\text{opt}}$ ; $I_{\text{C}} = 1.25$ mA; $V_{\text{CE}} = 6$ V; $T_{\text{amb}} = 25$ °C; $f = 2$ GHz	_	1.9	_	dB
P <sub>L1</sub>	output power at 1 dB gain compression	$I_C$ = 5 mA; $V_{CE}$ = 6 V; $R_L$ = 50 $\Omega$ ; $T_{amb}$ = 25 °C; f = 900 MHz	_	4	_	dBm
ITO	third order intercept point	note 2	-	10	_	dBm

Notes

1.  $G_{UM}$  is the maximum unilateral power gain, assuming  $S_{12}$  is zero and  $G_{UM}=10\log\frac{\left|S_{21}\right|^{2}}{(1-\left|S_{11}\right|^{2})(1-\left|S_{22}\right|^{2})}$  dB.

2.  $V_{CE}=6$  V;  $I_{C}=5$  mA;  $R_{L}=50$   $\Omega$ ;  $T_{amb}=25$  °C:

 $<sup>\</sup>begin{array}{ll} \text{2.} & \text{V}_{\text{CE}} = 6 \text{ V; I}_{\text{C}} = 5 \text{ mA; R}_{\text{L}} = 50 \text{ }\Omega; \text{ T}_{\text{amb}} = 25 \text{ }^{\circ}\text{C;} \\ & \text{f}_{\text{p}} = 900 \text{ MHz; f}_{\text{q}} = 902 \text{ MHz;} \\ & \text{measured at } 2f_{\text{p}} - f_{\text{q}} = 898 \text{ MHz and } 2f_{\text{q}} - f_{\text{p}} = 904 \text{ MHz.} \\ \end{array}$ 

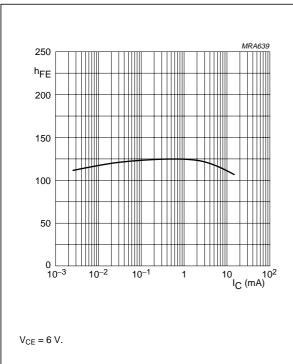
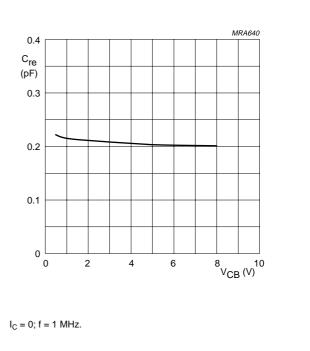
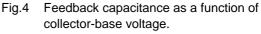
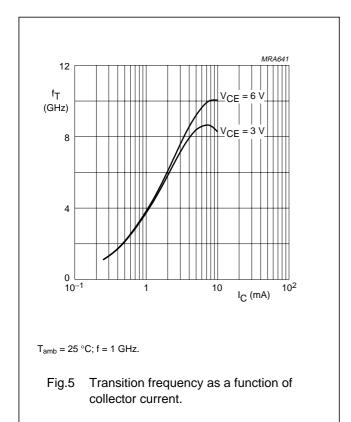
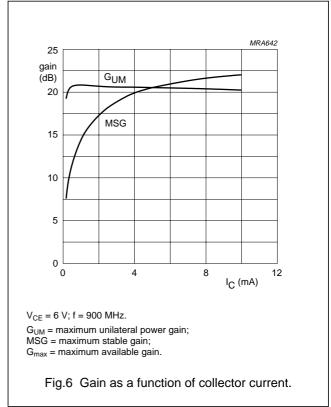


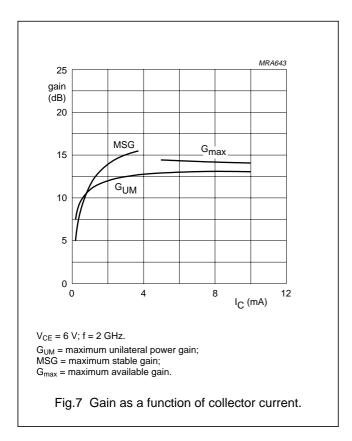
Fig.3 DC current gain as a function of collector current.

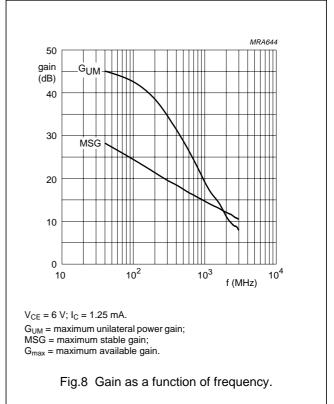


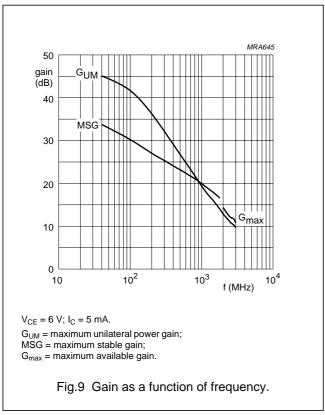


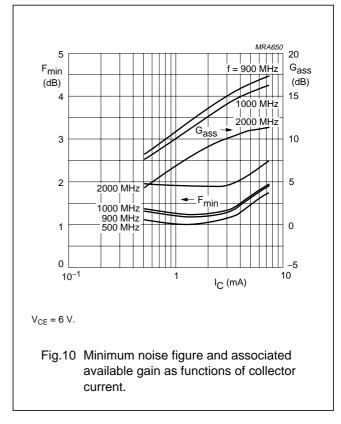


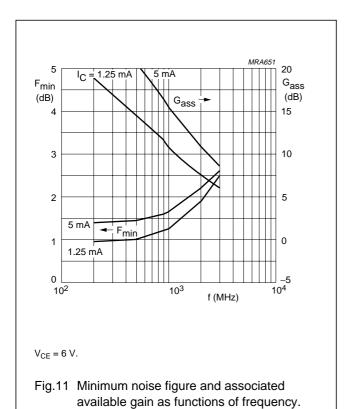


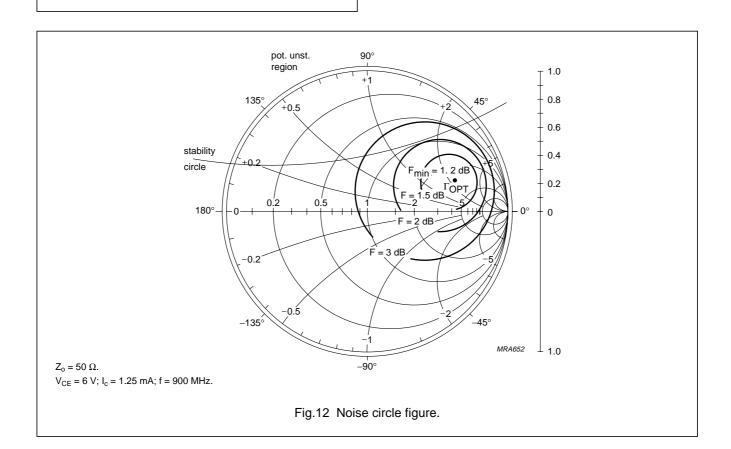


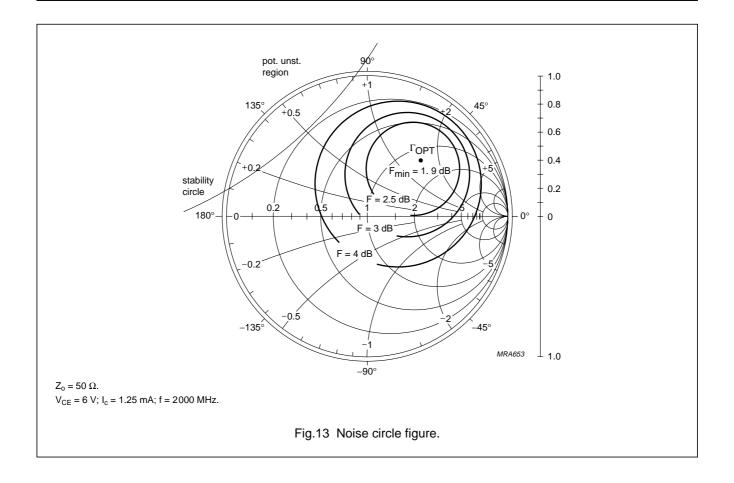


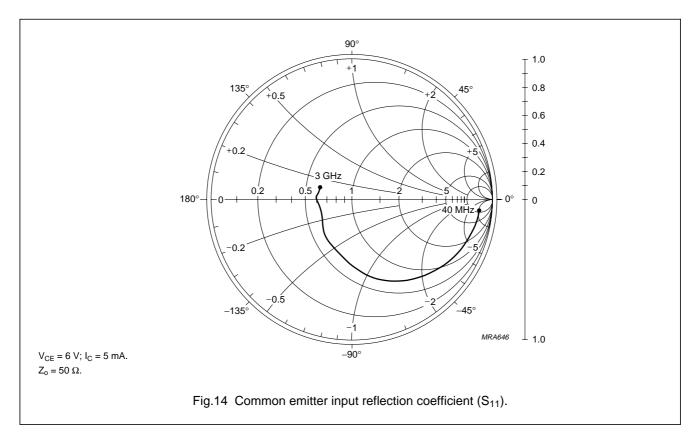


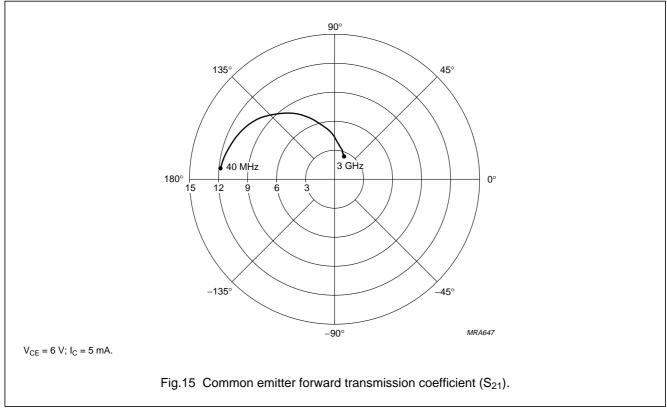


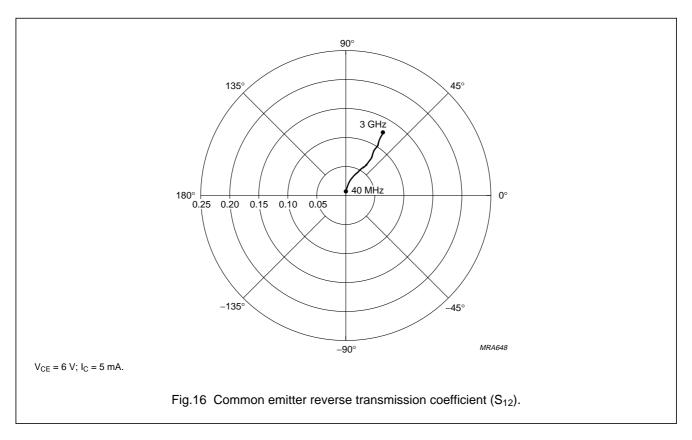


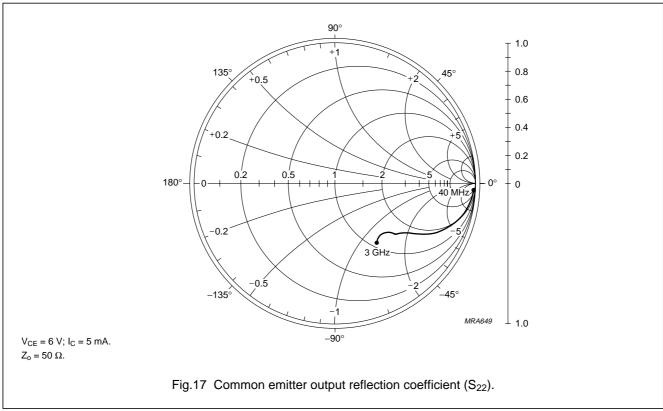










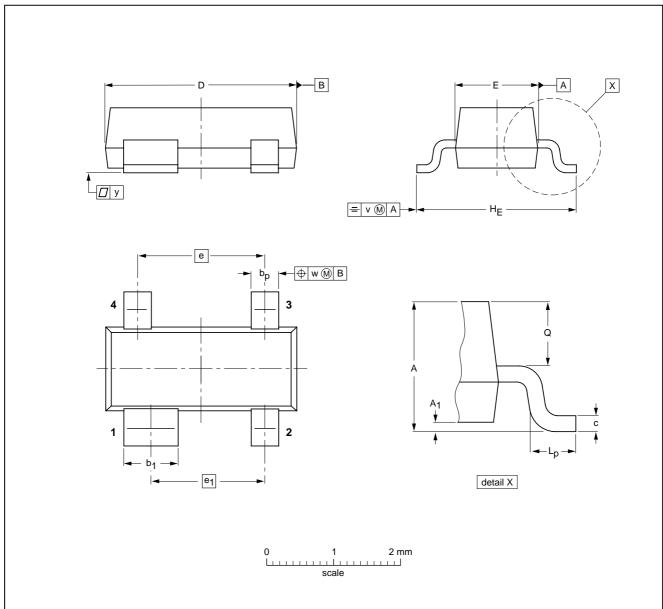


BFG505; BFG505/X

### **PACKAGE OUTLINE**

## Plastic surface mounted package; 4 leads

SOT143B



#### **DIMENSIONS** (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max	bp	b <sub>1</sub>	С	D	E	е	e <sub>1</sub>	HE	L <sub>p</sub>	Q	v	w	у
mm	1.1 0.9	0.1	0.48 0.38	0.88 0.78	0.15 0.09	3.0 2.8	1.4 1.2	1.9	1.7	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1	0.1

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT143B					97-02-28

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#### **Data sheet status**

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions"
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## **Revision history**

### **Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
BFG505_X_N_4	20071122	Product data sheet	-	BFG505_X_3
Modifications:	<ul> <li>Marking tab</li> </ul>	le on page 2; changed code		
BFG505_X_3 (9397 750 04348)	19981002	Product specification	-	BFG505XR_CNV_2
BFG505XR_CNV_2	19950901	Product specification	-	BFG505XR_1
BFG505XR_1	19921101	Product specification	-	-

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